

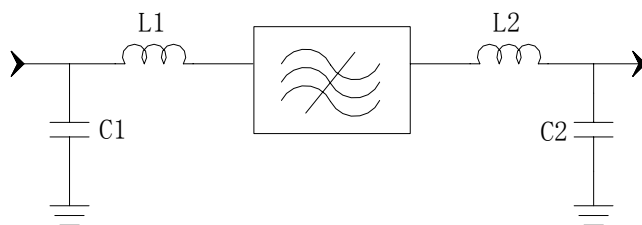
## Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	69.92	70	70.08
Insertion Loss	dB	—	11.9	14
1 dB Bandwidth	MHz	0.83	1.03	—
3 dB Bandwidth	MHz	1.5	1.53	—
40 dB Bandwidth	MHz	—	3.3	3.5
Passband Variation	dB	—	0.85	1
Group Delay Variation( $f_0 \pm 0.5\text{MHz}$ )	nsec	—	100	150
Phase Linearity ( $f_0 \pm 0.5\text{MHz}$ )	degree	—	3	5
Absolute Delay	usec	—	1.525	—
Ultimate Rejection	dB	—	41	—
Material Temperature coefficient	KHz/°C	-1.26		
Ambient Temperature	°C	25		
Package Size	SMP-53C (13.3 x 6.5 mm Nominal Footprint)			

### Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

## Matching Configuration




$$L1 = 180\text{nH} \quad L2 = 150\text{nH}$$

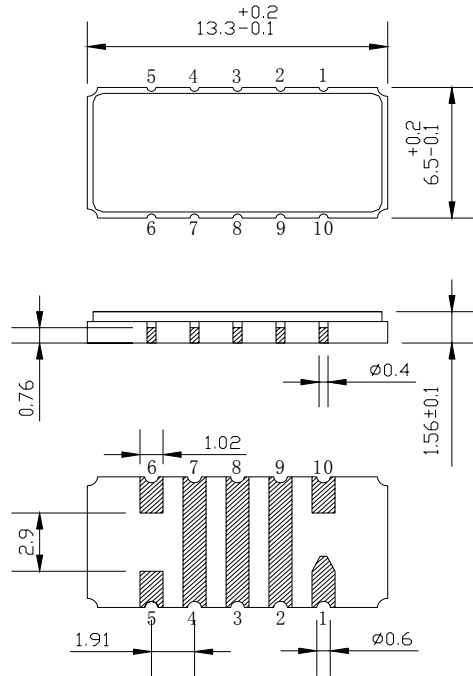
$$C1 = C2 = 36\text{pF}$$

**Source/Load Impedance = 50 ohm**

Notes - Component values may change depending on board layout.

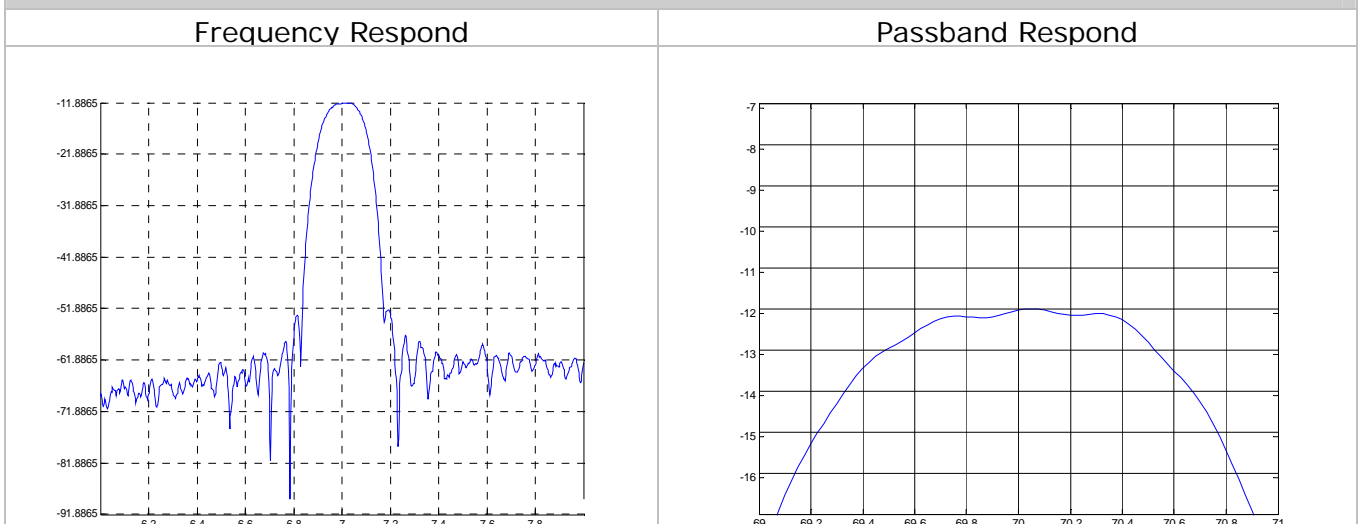
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Package Dimension



**Input:10**  
**Output:5**

Typical Performance



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